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Applications:

Dual 2-to 4-Line Decoder

Dual 1-to 4-Line Demultiplexer

3-to 8-Line Decoder

1-to 8-Line Demultiplexer

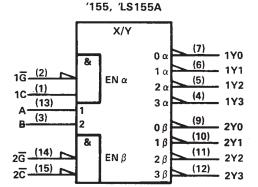
- Individual Strobes Simplify Cascading for Decoding or Demultiplexing Larger Words
- Input Clamping Diodes Simplify System Design
- Choice of Outputs: Totem Pole ('155, 'LS155A)
   Open-Collector ('156, 'LS156)

	TYPICAL AVERAGE	TYPICAL
TYPES	PROPAGATION DELAY	POWER
	3 GATE LEVELS	DISSIPATION
'155, '156	21 ns	125 mW
'LS155A	18 ns	31 mW
1.8156	32 ns	31 mW

#### description

These monolithic transistor-transistor-logic (TTL) circuits feature dual 1-line-to-4-line demultiplexers with individual strobes and common binary-address inputs in a single 16-pin package. When both sections are enabled by the strobes, the common binary-address inputs sequentially select and route associated input data to the appropriate output of each section. The individual strobes permit activating or inhibiting each of the 4-bit sections as desired. Data applied to input 1C is inverted at its outputs and data applied at 2C is not inverted through its outputs. The inverter following the 1C data input permits use as a 3-to-8-line decoder or 1-to-8-line demultiplexer without external gating. Input clamping diodes are provided on all of these circuits to minimize transmission-line effects and simplify system design.

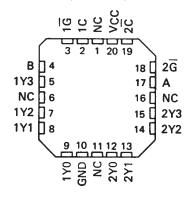
# logic symbols (2-line to 4-line decoder)†



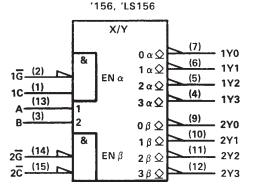
SN54155, SN54156, SN54LS155A, SN54LS156...J OR W PACKAGE SN74155, SN74156...N PACKAGE SN74LS155A, SN74LS156...D OR N PACKAGE (TOP VIEW)

1 <u>C</u>	1	U <sub>16</sub>	V <u>c</u> c
1Ğ	2	15	2C
В	3	14	2G
1Y3	4	13	Α
1Y2	5	12	2Y3
1Y1	6	11	2Y2
1Y0	7	10	2Y1
GND	8	9	2Y0

SN54LS155A, SN54LS156 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



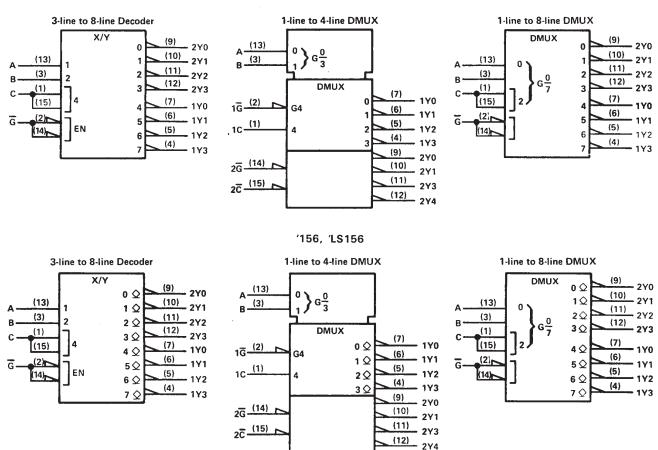
<sup>&</sup>lt;sup>†</sup>These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. For alternative symbols for other applications, see the following page.

Pin numbers shown are for D, J, N, and W packages.



#### additional logic symbols (alternatives) †

#### '155, 'LS155A



<sup>&</sup>lt;sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

#### schematics of inputs and outputs

155, 156 155 156 **EQUIVALENT OF EACH INPUT** TYPICAL OF ALL OUTPUTS TYPICAL OF ALL OUTPUTS 130  $\Omega$  NOM V<sub>C</sub>C 4 kΩ NOM OUTPUT INPUT OUTPUT



#### schematics of inputs and outputs (continued)

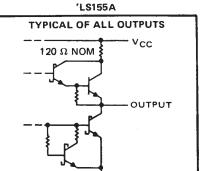
CS155A, 'LS156

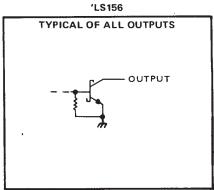
EQUIVALENT OF EACH INPUT

VCC

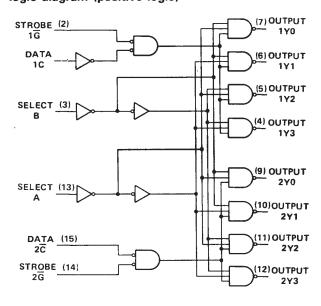
20 kΩ NOM

INPUT





#### logic diagram (positive logic)



# FUNCTION TABLES 2-LINE-TO-4-LINE DECODER OR 1-LINE-TO-4-LINE DEMULTIPLEXER

		INPUTS		OUTPUTS				
SEL	ECT	STROBE 1G	DATA 1C	1Y0	1Y1	1Y2	1Y3	
X	×	Н	X	Н	н	Н	Н	
L	L	L	н	Ł	Н	Н	Н	
L	Н	L	Н	н	L	н	Н	
н	L	L	н	н	н	L	Н	
н	Н	l L	н	н	н	н	L	
х	х	l x	L	1 н і	н	н	н	

		INPUTS		OUTPUTS					
SEL	ECT	STROBE	DATA	2Y0	2Y1	2Y2	2Y3		
В	Α	2G	2C						
Х	х	Н	x	н	н	н	Н		
L	L	L	L	L	н	н	н		
L	Н	L	L	н	L	н	н		
н	L	L	L	н	н	L	н		
н	Н	L	L	н	н	н	L		
х	Х	х	Н	н	Н	Н	Н		

# FUNCTION TABLE 3-LINE-TO-8-LINE DECODER OR 1-LINE-TO-8-LINE DEMULTIPLEXER

		INP	UTS				OUTP	UTS			
SE	LEC	:т	STROBE OR DATA	(0)	(1)	(2)	(3)	(4)	(5)	(6)	(7)
C†	В	A	G‡	2Y0	2Y1	2Y2	2Y3	1Y0	1Y1	1Y2	1Y3
Х	Х	Х	н	н	Н	Н	Н	Н	н	Н	н
L	L	L	L	L	Н	Н	Н	н	н	н	н
L	L	н	L	н	L	н	Н	н	н	н	н
L	Н	L	L	н	Н	L	Н	н	н	Н	н
L	Н	н	L	н	н	Н	Ł	Н	н	Н	н
н	L	L	L	н	Н	Н	н	L	н	Н	H
н	L	н	L	н	н	Н	Н	н	L	Н	Н
н	н	L	L	н	н	Н	н	н	н	Ł	н
Н	Н	Н	L	н	н	н	Н	н	н	н	L

 $<sup>^{\</sup>dagger}$ C = inputs 1C and 2 $\overline{C}$  connected together



 $<sup>\</sup>ddagger \overline{G}$  = inputs  $1\overline{G}$  and  $2\overline{G}$  connected together

H = high level, L = low level, X = irrelevant

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage: '155, '156	
'LS155A, 'LS156	
Off-state output voltage: '156	5.5 V
Operating free-air temperature range: SN54', SN54LS' Circuits	
SN74', SN74LS' Circuits	0°C to 70°C
	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN54155			SN74155			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	٧	
High-level output current, IOH			-800			-800	μΑ	
Low-level output current, IOL			16			16	mA	
Operating free-air temperature, TA	-55		125	0		70	°C	

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†			SN54155 SN74155			
				MIN	TYP‡	MAX		
$v_{IH}$	High-level input voltage			2			V	
VIL	Low-level input voltage			·		8.0	V	
VIK	Input clamp voltage	V <sub>CC</sub> = MIN, II	= -8 mA			-1.5	V	
Voн	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>I</sub> V <sub>IL</sub> = 0.8 V, I <sub>O</sub>		2.4	3.4		٧	
VOL	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>I</sub> V <sub>IL</sub> = 0.8 V, I <sub>O</sub>	H = 2 V,		0.2	0.4	v	
l <sub>l</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub>	= 5.5 V			1	mA	
ЧН	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub>	= 2.4 V			40	μА	
TIL	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub>	= 0.4 V			-1.6	mA	
1	Short circuit autaut au	V MAY	SN54155	-20		-55		
los	Short-circuit output current§	V <sub>CC</sub> = MAX	SN74155	-18		-57	mA	
1	Supply supply	V <sub>CC</sub> = MAX,	SN54155		25	35		
1CC	Supply current	See Note 2	SN74155		25	40	mA ·	

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC is measured with outputs open, A, B, and 1C inputs at 4.5 V, and 2C, 1G, and 2G inputs grounded.

# switching characteristics, VCC = 5 V, TA = 25 °C

PARAMETER	FROM	TO	LEVELS	TEST CONDITIONS	SN54155 SN74155			UNIT
	(INPUT)	(OUTPUT)	OF LOGIC		MIN	TYP	MAX	
<sup>t</sup> PLH	A, B, 2 <del>C</del> , 1 <u>G</u> , or 2 <u>G</u>	Y	2	C <sub>L</sub> = 15 pF, R <sub>L</sub> = 400 Ω, See Note 3		13	20	ns
<sup>t</sup> PHL,	A, B, 2 <del>C</del> , 1 <del>G</del> , or 2 <del>G</del>	Υ	. 2			18	27	ns
<sup>t</sup> PLH	A or B	У	3			21	32	ns
<sup>t</sup> PHL	A or B	Υ	3			21	32	ns
<sup>t</sup> PLH	1C	Υ	3			16	24	ns
· tphL	1C	Y	3			20	30	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup>All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup>Not more than one output should be shorted at a time.

#### recommended operating conditions

		SN5415	6	SN74156			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNITI
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, VOH			5.5			5.5	٧
Low-level output current, IOL			16			16	mA
Operating free-air temperature, TA	-55		125	0		70	°c

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN5415	6	
	PARAMETER	TEST CONDITIONS†	;	SN7415	6	UNIT
			MIN	TYP‡	MAX	
VIH	High-level input voltage		2			٧
VIL	Low-level input voltage				0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>1</sub> = -8 mA			-1.5	V
1	Wink to all puts to company	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,			250	μА
ЮН	High-level output current	$V_{1L} = 0.8 \text{ V}, V_{OH} = 5.5 \text{ V}$	-			μΑ.
.,		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,	Ī	0.2	0.4	V
VOL	Low-level output voltage	V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16 mA		0.2	0.4	ľ
П	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>1</sub> = 5.5 V			1	mA
Чн	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V			40	μА
IIL.	Low-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 0.4 V			-1.6	mA
		V <sub>CC</sub> = MAX, SN54156		25	35	
1CC	Supply current	See Note 2 SN74156		25	40	mA

 $<sup>^{\</sup>dagger}_{\cdot}$  For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $\ddagger$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. NOTE 2: I<sub>CC</sub> is measured with outputs open, A, B, and 1C inputs at 4.5 V, and 2C, 1G, and 2G inputs grounded.

### switching characteristics, VCC = 5 V, TA = 25 °C

PARAMETER§	FROM	то	LEVELS OF LOGIC	TEST CONDITIONS	SN7415		SN54156 SN74156			UNIT
	(INPUT)	(OUTPUT)	OF LOGIC		MIN	TYP	MAX			
<sup>t</sup> PLH	A, B, 2 <del>C</del> , 1 <del>G</del> , or 2 <del>G</del>	Y	2	C <sub>L</sub> = 15 pF,		15	23	ns		
<sup>†</sup> PHL	A, B, 2 <del>C</del> , 1 <del>G</del> , or 2 <del>G</del>	Υ	2			20	30	ns		
tPLH	A or B	У	3	$R_L = 400 \Omega$ , See Note 3		23	34	ns		
<sup>t</sup> PHL	A or B	Y	3	See Note 3		23	34	ns		
tpLH	1C	Y	3			18	27	ns		
tPHL	1C	Υ	3			22	33	ns		

 $<sup>^{\</sup>S}$ tpLH = propagation delay time, low-to-high-level output tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS155A, SN74LS155A DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

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#### recommended operating conditions

	SN	154LS1!	55A	SN	5A	UNIT	
	MIN	NOM	MAX	MIN	NOM	MAX	ONT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			400			-400	μА
Low-level output current, IOL			4			8	mA
Operating free-air temperature, TA	-55		125	0		70	°c

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				+	SN	154LS19	55A	SN	174LS1	55A	UNIT
	PARAMETER	TES	ST CONDITIONS	5'	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage	***			2			2			V
VIL	Low-level input voltage						0.7			0.8	٧
	Input clamp voltage	V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.5			-1.5	٧
	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>IH</sub> = 2 V, , I <sub>OH</sub> = -400 μ/	1	2.5	3.4		2.7	3.4		٧
			V <sub>IH</sub> = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	Low-level output voltage	VIL = VIL max	:	IOL = 8 mA					0.35	0.5	
ų	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V				0.1			0.1	mA
ΊΗ	High-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V				20			20	μΑ
IIL.	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				-0.4			-0.4	mA
	Short-circuit output current §	V <sub>CC</sub> = MAX			- 20		- 100	- 20		- 100	mA
Icc	Supply current	V <sub>CC</sub> = MAX,	See Note 2			6.1	10		6.1	10	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC is measured with outputs open, A, B, and 1C inputs at 4.5 V, and 2C, 1G, and 2G inputs grounded.

## switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER¶	FROM	то	LEVELS	TEST CONDITIONS		54LS15 74LS15		UNIT
	(INPUT)	(OUTPUT)	OF LOGIC		MIN	TYP	MAX	
<sup>t</sup> PLH	A, B, 2 <del>C</del> , 1 <u>G</u> , or 2 <u>G</u>	Y	2			10	15	ns
<sup>t</sup> PHL	A, B, 2C̄, 1Ḡ, or 2Ḡ	Y	2	C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ,		19	30	ns
tPLH	A or B	Υ	3	See Note 3		17	26	ns
tPHL	A or B	Y	3	See Note S		19	30	ns
tPLH	1C	Y	3			18	27	
t <sub>PHL</sub>	1C	Y	3			18	27	ns

 $<sup>\</sup>mathbf{f}_{tpLH}$  = propagation delay time, low-to-high-level output



<sup>‡</sup>All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time.

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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#### recommended operating conditions

	SI	SN54LS156				SN74LS156			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT		
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V		
High-level output voltage, VOH			5.5			5.5	V		
Low-level output current, IOL			4			8	mA		
Operating free-air temperature, TA	-55		125	0		70	°C		

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				. +	SI	N54LS1	56	SI	N74LS1	56	דומט -
	PARAMETER	TEST	CONDITIONS	5'	MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	UNIT
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.5			-1.5	٧
ЮН	High-level output current	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max,	V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 5.5 V				100			100	μА
VOL	Low-level output voltage	V <sub>CC</sub> = MIN,	V <sub>1H</sub> = 2 V,	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	4 V
		V <sub>IL</sub> = V <sub>IL</sub> max		IOL = 8 mA					0.55	0.5	
l <sub>I</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
ΉΗ	High-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	μА
IIL.	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				-0.4			-0.4	mA
1cc	Supply current	V <sub>CC</sub> = MAX,	See Note 2			6.1	10		6.1	10	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: I<sub>CC</sub> is measured with outputs open, A, B, and 1C inputs at 4.5 V, and 2C, 1G, and 2G inputs grounded.

# switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER§	FROM	то	LEVELS	TEST CONDITIONS	ì	54LS1 74LS1		UNIT
PARAMETER*	(INPUT)	(OUTPUT)	OF LOGIC		MIN	TYP	MAX	<u> </u>
<sup>t</sup> PLH	A, B, 2C 1G, or 2G	Y	2			25	40	ns
<sup>t</sup> PHL	A, B, 2C, 1G, or 2G	Y	2	$C_L = 15  pF$ , $R_L = 2  k\Omega$ ,		34	51	ns
tPLH	A or B	Y	3	See Note 3		31	46	ns
tPHL.	A or B	Y	3	See Note 3		34	51	ns
tPLH	1C	Y	3			32	48	ns
<sup>t</sup> PHL	1C	Y	3			32	48	ns

 $<sup>{}^{\</sup>S}tPLH$  = propagation delay time, low-to-high-level output



 $<sup>\</sup>ddagger$ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





17-May-2014

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9750801Q2A	ACTIVE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		Samples
5962-9750801QEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9750801QE A SNJ54LS155AJ	Samples
5962-9750801QEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9750801QE A SNJ54LS155AJ	Samples
5962-9750801QFA	ACTIVE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		Samples
5962-9750801QFA	ACTIVE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		Samples
SN54155J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54155J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54LS155AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS155AJ	Samples
SN54LS155AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS155AJ	Samples
SN54LS156J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS156J	Samples
SN54LS156J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS156J	Samples
SN74155N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74155N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74155N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74155N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74156N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74156N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS155AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155ADE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS155ADE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		Samples



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS155ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155ADRE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS155ADRE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS155ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS155A	Samples
SN74LS155AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS155AN	Samples
SN74LS155AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS155AN	Samples
SN74LS155ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS155AN	Samples
SN74LS155ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS155AN	Samples
SN74LS155ANSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS155A	Samples
SN74LS155ANSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS155A	Samples
SN74LS155ANSRE4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS155ANSRE4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS155ANSRG4	ACTIVE	so	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS155ANSRG4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS156D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Samples



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Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)					(2)	(6)	(3)		(4/5)	
SN74LS156D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sample
SN74LS156DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sampl
SN74LS156DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sampl
SN74LS156DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS156	Sampl
SN74LS156N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS156N	Sampl
SN74LS156N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS156N	Sampl
SN74LS156N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS156N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS156NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS156N	Samp
SN74LS156NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS156N	Samp
SN74LS156NSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS156	Samp
SN74LS156NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS156	Samp





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS156NSRE4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS156NSRE4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS156NSRG4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SN74LS156NSRG4	ACTIVE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		Samples
SNJ54155J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54155J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54155W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54155W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS155AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9750801Q2A SNJ54LS 155AFK	Sample
SNJ54LS155AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9750801Q2A SNJ54LS 155AFK	Sample
SNJ54LS155AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9750801QE A SNJ54LS155AJ	Sample
SNJ54LS155AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9750801QE A SNJ54LS155AJ	Sample
SNJ54LS155AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9750801QF A SNJ54LS155AW	Sample
SNJ54LS155AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9750801QF A SNJ54LS155AW	Sample
SNJ54LS156FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS156FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS156J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS156J	Sample
SNJ54LS156J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS156J	Sample



### PACKAGE OPTION ADDENDUM

17-May-2014

Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54LS156W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS156W	Samples
SNJ54LS156W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS156W	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder humps used between the die and package, or 2) lead-based die adhesive used between

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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### **PACKAGE OPTION ADDENDUM**

17-May-2014

#### OTHER QUALIFIED VERSIONS OF SN54155, SN54LS155A, SN54LS156, SN74155, SN74LS155A, SN74LS156:

• Catalog: SN74155, SN74LS155A, SN74LS156

• Military: SN54155, SN54LS155A, SN54LS156

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS155ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS156DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS156NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS155ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS156DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS156NSR	SO	NS	16	2000	367.0	367.0	38.0

## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F16)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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